

1. General description

Silicon Carbide Schottky diode in a TO247-2L plastic package, designed for high frequency switched-mode power supplies.



AEC - Q101 Qualified



2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability I_{FSM}
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- AEC-Q101 qualified

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives
- On board charger

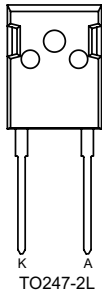

4. Quick reference data

Table 1. Quick reference data

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Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage			650			V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 127 °C; Fig. 1 ; Fig. 2 ; Fig. 3		20			A
T _j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 20 A; T _j = 25 °C; Fig. 5		-	1.26	1.40	V
		I _F = 20 A; T _j = 150 °C; Fig. 5		-	1.35	1.55	V
Dynamic characteristics							
Q _r	recovered charge	I _F = 20 A; dI _F /dt = 500 A/μs; V _R = 400 V; T _i = 25 °C; Fig. 7		-	48	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC6D20650W-A	TO247-2L	WNSC6D20650W-A6Q	Tube	30	TO247L-2L	10-Nov-2020

7. Marking

Table 4. Marking codes

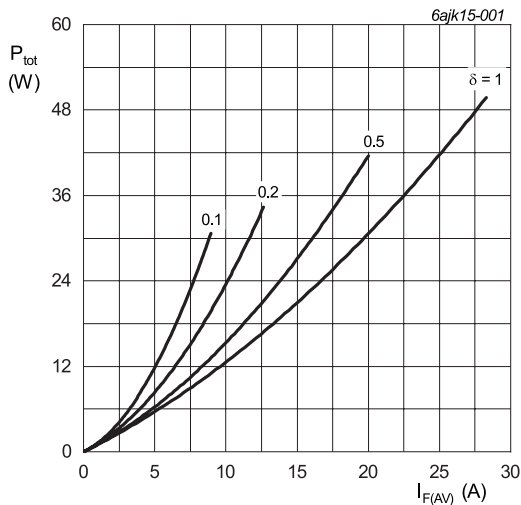
Type number	Marking codes
WNSC6D20650W-A	WNSC6D 20650W-A

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			650	V
V_{RWM}	crest working reverse voltage			650	V
V_R	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 127\text{ }^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3		20	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 127\text{ }^{\circ}\text{C}$; square-wave pulse		40	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse		140	A
		$t_p = 10\text{ }\mu\text{s}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; square-wave pulse		1000	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 10\text{ ms}$		98	A^2s
T_{stg}	storage temperature			-55 to 175	$^{\circ}\text{C}$
T_j	junction temperature			-55 to 175	$^{\circ}\text{C}$



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
 $V_o = 0.984\text{ V}; R_s = 0.0274\text{ }\Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

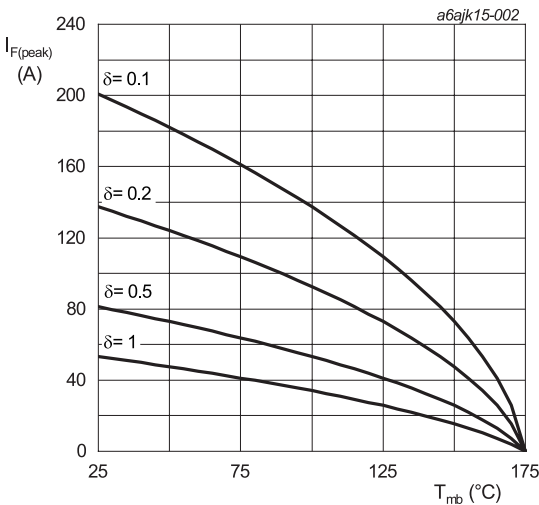


Fig. 2. Current derating as a function of mounting base temperature

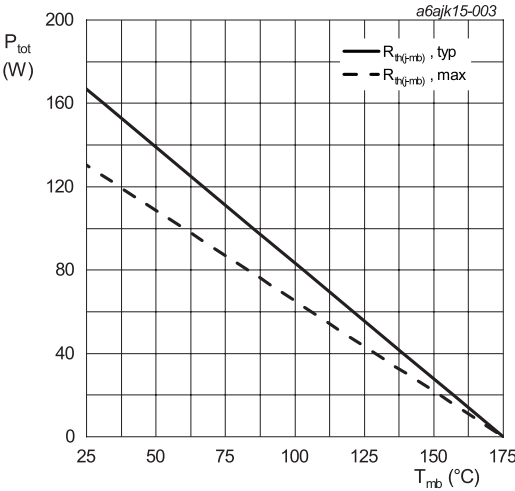


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	0.9	1.15	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

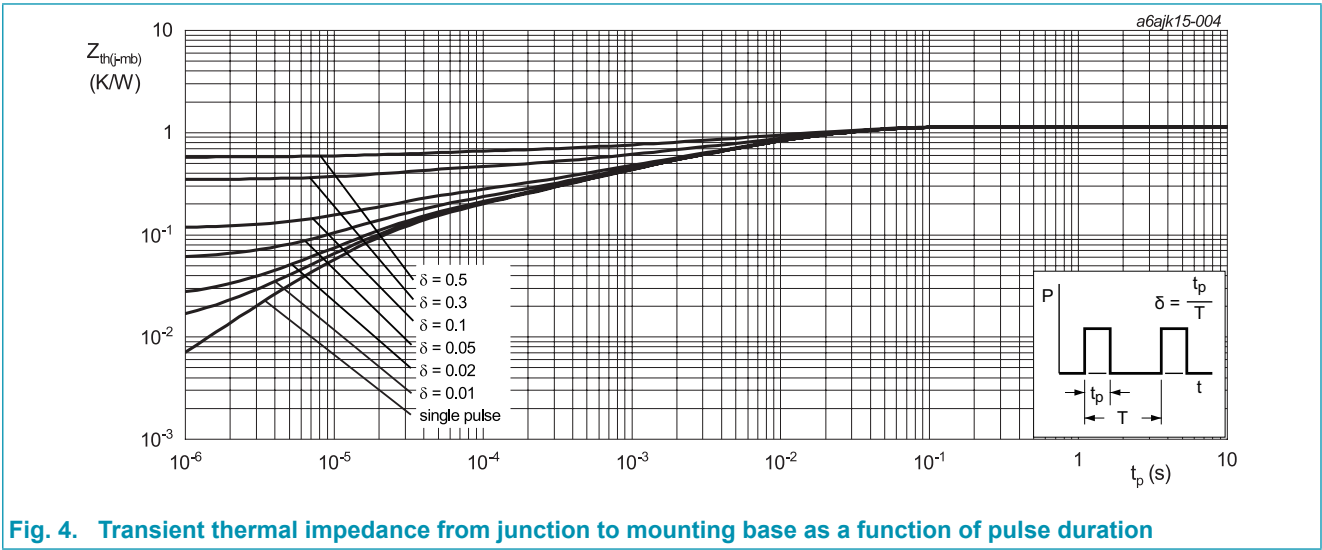
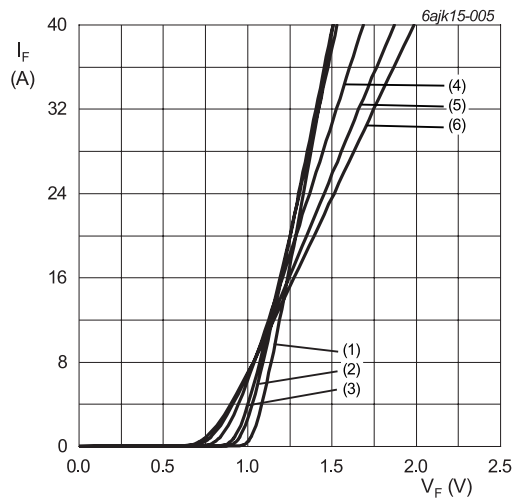


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 20 A; T _J = 25 °C; Fig. 5		-	1.26	1.40	V
		I _F = 20 A; T _J = 150 °C; Fig. 5		-	1.35	1.55	V
		I _F = 20 A; T _J = 175 °C; Fig. 5		-	1.40	1.60	V
I _R	reverse current	V _R = 650 V; T _J = 25 °C; Fig. 6		-	2	100	μA
		V _R = 650 V; T _J = 175 °C; Fig. 6		-	30	400	μA
Dynamic characteristics							
Q _r	recovered charge	I _F = 20 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _J = 25 °C; Fig. 7		-	48	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _J = 25 °C		-	1005	-	pF
		f = 1 MHz; V _R = 300 V; T _J = 25 °C		-	110	-	pF
		f = 1 MHz; V _R = 600 V; T _J = 25 °C		-	102	-	pF
E _{as}	non-repetitive avalanche energy	I _R = 7.8 A; L = 5 mH; T _{J(init)} = 25 °C		150	-	-	mJ



V_o = 0.984 V; R_s = 0.0274 Ω
(1) T_J = -55 °C; typical values
(2) T_J = 0 °C; typical values
(3) T_J = 25 °C; typical values
(4) T_J = 100 °C; typical values
(5) T_J = 150 °C; typical values
(6) T_J = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

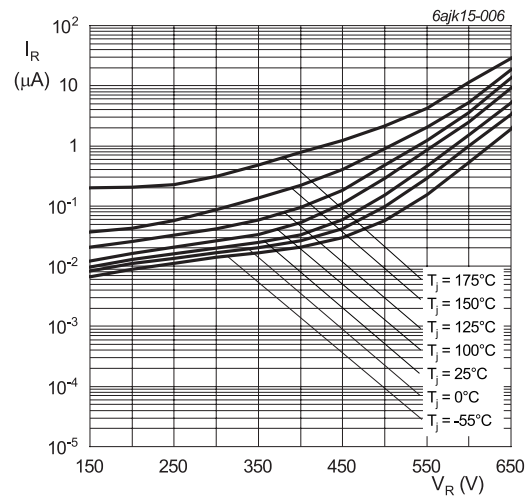


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

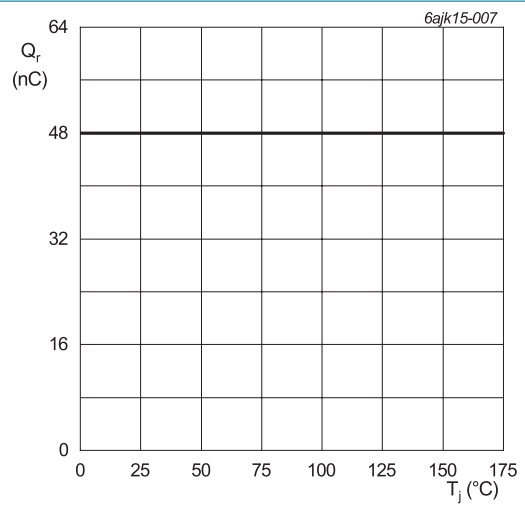


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended through-hole package; heatsink mounted;1 mounting hole; 2 leads TO-247

TO247-2L

The technical drawing illustrates the package outline for the WNSC6D20650W-A. It includes three views: a top view showing the mounting hole (Ø) and leads (p, q); a side view showing the package height (D, D1, D2) and lead dimensions (A, A1, b, b1, c, e); and a front view showing the package width (E, E1, E2, E3) and lead dimensions (L, L1). Dimensions are provided in millimeters (mm) and inches (BSC).

UNIT	A	A ₁	b	b ₁	c	D	D ₁ ②	D ₂	E	E ₁	E ₂	E ₃	e	L	L ₁	P ₂	p	Q	q	Ø
mm	5.20 4.70	2.10 1.90	1.40 1.00	2.20 1.80	0.70 0.50	20.60 20.30	16.20 16.87	1.20 0.80	15.75 15.45	14.22 13.82	5.20 4.80	1.80 1.40	10.90 BSC	20.72 20.22	4.75 4.25	3.60 3.40	3.70 3.50	2.60 2.20	6.18 5.78	7.30 7.10

Note:

1. Mold resin protrusion max 0.127mm.

2. Metal exposed with Sn plating.

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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